

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3	"580740".ap.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 13:41
L2	8	("20020072215"   "20040018660"   "5160409"   "6316831").PN.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:21
L3	1733	("205"/\$.ccls. "204"/\$. ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$. ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder near3 bump and \$5resist and barrier	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:33
L4	472	("205"/\$.ccls. "204"/\$. ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$. ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder near3 bump and \$5resist and barrier and seed and copper and nickel	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:34
L5	460	("205"/\$.ccls. "204"/\$. ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$. ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder near3 bump and \$5resist and barrier and seed and copper and nickel and etch\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:34

L6	198	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder near3 bump and \$5resist and barrier and seed and copper and nickel and etch\$4	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:36
L7	190	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder near3 bump and \$5resist and barrier and seed and copper and nickel and etch\$4 same (seed barrier copper)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 14:37
L8	40	("20020068425"   "20020079576"   "20020190028"   "20030057551"   "5268072"   "5492235"   "5503286"   "5543032"   "5629564"   "5767010"   "5800726"   "5855993"   "5885891"   "5937320"   "6162652"   "6187680"   "6222279"   "6277669"   "6293457"   "6319846"   "6332988"   "6333559"   "6358836"   "6489229"   "6501185"   "6536653"   "6541366").PN. OR ("6622907").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2009/03/02 14:47

L10	17	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder near3 bump and \$5resist and barrier and seed and copper and nickel and etch\$4 same (seed barrier copper) and current adj2 density	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:16
L11	4	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder near3 bump and \$5resist and barrier and seed and copper and nickel and (current adj2 density) with (increas\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:22
L12	3	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder near3 bump and \$5resist and barrier and seed and copper and nickel and (current adj2 density) near5 (increas\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:23
L13	0	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) same solder near3 bump and \$5resist and barrier and seed and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:28

L14	0	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder near3 bump and \$5resist and barrier and seed and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:28
L15	13	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and \$5resist and barrier and seed and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:29
L16	4	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder and \$5resist and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:36
L17	487	("205"/\$.ccls. "204"/\$.ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$.ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:40

L18	16	("205"/\$.ccls. "204"/\$. ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$. ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and solder and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:40
L19	11	("205"/\$.ccls. "204"/\$. ccls. "438"/\$.ccls. "257"/\$.ccls. "216"/\$. ccls.) and (electrolytic electrochemic\$4 electrodeposit\$5 electroplat\$5) and bump and (current adj2 density) near5 (increas\$3) with rate	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/03/02 16:44

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